EXPRESS MAIL LABEL NO. 516214740 US

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1. Name of conveying party(ies):
Tan-Chen Lee

Additional name(s) of conveying party(ies) attached? ☐ Yes ☑ No

2. Name and address of receiving party(ies)
Name: Taiwan Semiconductor Manufacturing Co., Ltd.
Internal Address:
Street Address: No. 8, Li-Hsin Road 6
Science Based Industrial Park
City: Hsin-Chu State: Zip:
Country: Taiwan 300-77 R.O.C.
Additional name(s) & address(es) attached? ☐ Yes ☑ No

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3. Nature of conveyance:
☑ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: 03/01/2005

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is: 03/01/2005
A. Patent Application No.(s)
B. Patent No.(s)
Additional numbers attached? ☐ Yes ☑ No

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: Steven E. Koffs, Esquire
Internal Address: Duane Morris LLP
Street Address: One Liberty Place
City: Philadelphia State: PA Zip: 19103

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41)..............$ 40.00
☐ Enclosed
☑ Authorized to be charged to deposit account

8. Deposit account number:
04-1679

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9. Signature.
Steven E. Koffs
Name of Person Signing
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Total number of pages including cover sheet, attachments, and documents: 3

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EXPRESS MAIL LABEL NO. EV 516214740US ATTORNEY DOCKET NO. 2003.0004/1085.00219

ASSIGNMENT AND AGREEMENT

For value received, I, **Tan-Chen Lee**, hereby sell, assign and transfer to **Taiwan Semiconductor Manufacturing Co., Ltd.**, with its principal place of business located at No. 8, Li-Hsin Road 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to **METHODS FOR ENHANCING THE FORMATION OF NICKEL MONO-SILICIDE BY REDUCING THE FORMATION OF NICKEL DI-SILICIDE** described in U.S. provisional application Serial No. 60/576,559, filed June 2, 2004, and in a non-provisional application for Letters Patent of the United States and all the rights and privileges in said application and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof that may be granted in the United States for said inventions; and I also concurrently hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

I authorize Taiwan Semiconductor Manufacturing Co., Ltd. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from me, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

I hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Taiwan Semiconductor Manufacturing Co., Ltd. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

I request that any and all patents for said inventions be issued to Taiwan Semiconductor Manufacturing Co., Ltd. in the United States and in all countries foreign to the United States, or to such nominees as Taiwan Semiconductor Manufacturing Co., Ltd. may designate.

EXPRESS MAIL LABEL NO. EV 516214740US **ATTORNEY DOCKET NO. 2003.0004/1085.00219**

I agree that, when requested, I shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Inventor

Dated: Mar 1, 2005

Tan-Chen Lee

Residence:

No. 19, Ln. 13, Kwangkua St, Panchiao, Taiwan R.O.C